



[ADD](#) |
 [EMAIL](#) |
 [g+](#) |
 [in](#) |
 [twitter](#) |
 [f](#)

MTFC8GLWDM-3M AIT Z

[DATA SHEETS \(1\)](#) |
 [SPECS](#) |
 [ROHS CERTIFICATES](#) |
 [DOCUMENTATION & SUPPORT](#) |
 [PARTS WITH THE SAME DATA SHEET \(4\)](#) |
 [WHERE TO BUY](#)

Data Sheets (1)

Data Sheet

🔒

4-32GB eMMC v4.51 TFBGA153 & TFBGA169 (Automotive, IT) Data Sheet

Automotive
Embedded Memory Solutions
eMMC
Managed NAND

MTFC4GMWDM-3M AIT, MTFC8GLWDM-3M AIT Z, MTFC8GLWDM-AIT Z, MTFC16GLWDM-4M AIT Z, MTFC32GJWEF-4M AIT Z (Controller ID= W)

File Type: PDF **Updated:** 07/2015

VIEW

DOWNLOAD

Specs

Orderable Parts for: MTFC8GLWDM-3M AIT Z

SEE ALL 8GB E.MMC MEMORY PARTS

	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
MTFC8GLWDM-3M AIT Z	Production	N/A	HBBSN	N/A	N/A	No		N/A

Detailed Specifications

Part Status Code	Production	Applications	Automotive	Density	8GB	Bus Width	x8
Voltage	2.7V-3.6V	Package	TFBGA	Pin Count	153-ball	Package Size	11.5 x 13 x 1.2
MMC Interface	4.5	RoHS	Yes	Operating Temp	-40C to +85C		

RoHS Certificates

RoHS Certificates

RoHS Certificate of Compliance (PDF)

MTFC8GLWDM 3M AIT Z

Part-specific certification of how this product meets the requirements of the current DIRECTIVE 2002/95/EC, a.k.a. Restriction of Hazardous Substances (RoHS) Directive.

File Type: (PDF)

Updated: 02/2017

DOWNLOAD

RoHS Certificates

China RoHS Certificate (PDF)

MTFC8GLWDM 3M AIT Z

Part-specific certification as required by China's Management Methods for Controlling Pollution by Electronic Information Products.

File Type: (PDF)

Updated: 02/2017

DOWNLOAD

Documentation & Support

[See All Documentation](#)

Technical Notes

SEARCH (54) TECHNICAL NOTES

Technical Notes

TN-00-08: Thermal Applications (PDF)

DRAM
Managed NAND
Multichip Packages
NAND Flash
[See More Tags](#)

(TN-00-08) Describes some considerations in thermal applications for Micron memory devices

File Type: PDF

Updated: 01/24/2017

DOWNLOAD

Technical Notes



TN-13-49: SLC NAND Device Refresh (PDF)

NAND Flash
SLC NAND

(TN-13-49) This technical note discusses the adverse effects of high temperature and PROGRAM/ERASE (P/E) cycles on flash memory data retention and how the REFRESH operation can be used to mitigate these adverse effects.

File Type: PDF

Updated: 10/31/2016

DOWNLOAD

TN-29-14: NAND Flash Performance Increase Using PROGRAM PAGE CACHE MODE Command (PDF)

NAND Flash

(TN-29-14) This technical note highlights the significant performance gains realized when using the PROGRAM PAGE CACHE MODE command in Micron's NAND Flash devices.

File Type: PDF

Updated: 09/29/2016

[DOWNLOAD](#)

Technical Notes

TN-29-25: Improving NAND Flash Performance Using Two-Plane Command Enabled Micron Devices (PDF)

NAND Flash

(TN-29-25) This technical note describes the performance benefits of Micron two-plane commands and provides implementation guidelines for making the best use of two-plane capabilities.

File Type: PDF

Updated: 09/29/2016

[DOWNLOAD](#)

Technical Notes

TN-29-42: Wear-Leveling Techniques in NAND Flash Devices (PDF)

NAND Flash

(TN-29-42) This technical note highlights the importance of wear leveling, explains two wear-leveling techniques, and discusses implementing wear leveling.

File Type: PDF

Updated: 09/29/2016

[DOWNLOAD](#)[SEARCH \(54\) TECHNICAL NOTES](#)

Customer Service Note

Customer Service Note

Customer Service Note

Shipping Quantities (PDF)

DRAM
DRAM Modules
Hybrid Memory Cube
Multichip Packages
[See More Tags](#)

(CSN-04) This customer service note describes the standard shipping quantity, box quantity, and types such as tape and reel for Micron's products.

File Type: PDF

Updated: 07/18/2016

[DOWNLOAD](#)

Customer Service Note

Wafer Packaging and Packaging Materials (PDF)

DRAM
NAND Flash

(CSN-20) Provides complete shipping and recycling information about each of the materials used for shipping Micron's products.

SEARCH (2) CUSTOMER SERVICE NOTE

Parts with the same Data Sheet (4)

	MTFC8GLWDM-3M AIT Z (Current)	MTFC4GMWDM-3M AIT	MTFC16GLWDM-4M AIT Z	MTFC32GJWEF-4M AIT Z
Part Status Code	Production	Production	Production	Production
Applications	Automotive	Automotive	Automotive	Automotive
Density	8GB	4GB	16GB	32GB
Bus Width	x8	x8	x8	x8
Voltage	2.7V-3.6V	2.7V-3.6V	2.7V-3.6V	2.7V-3.6V
Package	TFBGA	TFBGA	TFBGA	TFBGA
Pin Count	153-ball	153-ball	153-ball	169-ball
Package Size	11.5 x 13 x 1.2	11.5 x 13 x 1.2	11.5 x 13 x 1.2	14 x 18 x 1.2
MMC Interface	4.5	4.5	4.5	4.5
RoHS	Yes	Yes	Yes	Yes
Operating Temp	-40C to +85C	-40C to +85C	-40C to +85C	-40C to +85C



Where to Buy

Orderable Parts

	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
MTFC8GLWDM-3M AIT Z	Production	N/A	HBBSN	N/A	N/A	No		N/A

[CONTACT A REP](#)

Your Region:

	VIEW
	VIEW

[See All Distributors](#)

- | | | | | |
|-----------------------------|------------------------------------|-----------------------|-------------------------|------------------------------|
| Solutions | Memory and Storage Products | About | Support | Contact Us |
| Automotive Memory Solutions | DRAM | Our Company | Sales Network | Sales Network |
| Client SSD Storage | DRAM Modules | News and Events | Authorized Distributors | Authorized Sales |
| Data Center | NAND Flash | Micron Blogs | Contact Us | Site Map |
| Embedded Memory Solutions | Managed NAND | Micron Foundation | Jobs | Surplus Equipment |
| Enterprise SSD Storage | NOR Flash | History of Innovation | | Terms of Use |
| Mobile Memory Solutions | Hybrid Memory Cube | Locations | | Terms and Conditions of Sale |
| Networking Innovations | Multichip Packages | Our Commitment | | Privacy |
| Supercomputing Memory | Solid State Drives | Investor Relations | | |
| Ultrathin Solutions | | | | |

